

Description

This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirements of automotive applications.

Features

- $BV_{CEO} > -60V$
- $I_C = -3A$ High Continuous Current
- $I_{CM} = -6A$ Peak Pulse Current
- Low Saturation Voltage $V_{CE(SAT)} < -300mV @ -1A$
- Complementary NPN Type: FZT651Q
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

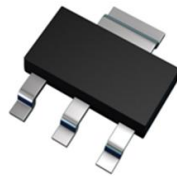
Applications

- Automotive Lighting
- MOSFET and IGBT Gate Driving

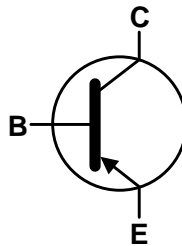
Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 Ⓔ3
- Weight: 0.112 grams (Approximate)

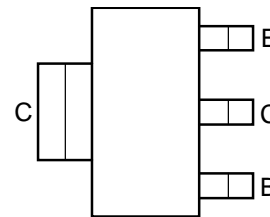
SOT223



Top View



Device Symbol



Top View Pin-Out

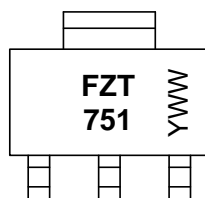
Ordering Information (Note 5)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
FZT751QTA	Automotive	FZT751	7	12	1,000
FZT751QTC	Automotive	FZT751	13	12	4,000

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Please refer to <https://www.diodes.com/quality/>.
 5. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

SOT223



FZT 751 = Product Type Marking Code
 YWW = Date Code Marking
 Y or \bar{Y} = Last Digit of Year (ex: 8 = 2018)
 WW or $\bar{W}W$ = Week Code (01 to 53)

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-80	V
Collector-Emitter Voltage	V _{CEO}	-60	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	I _C	-3	A
Peak Pulse Current	I _{CM}	-6	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

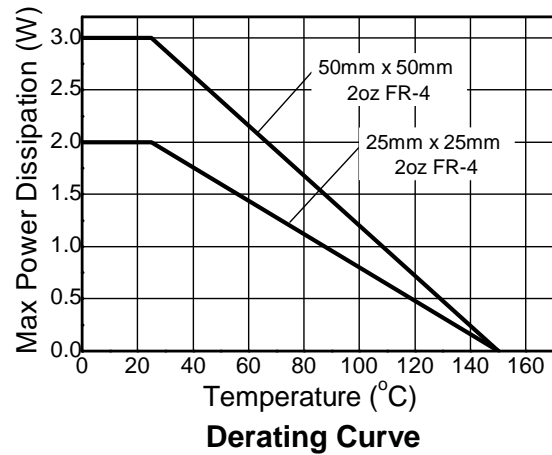
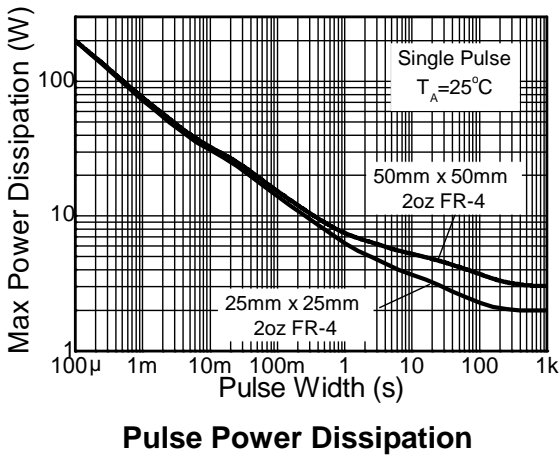
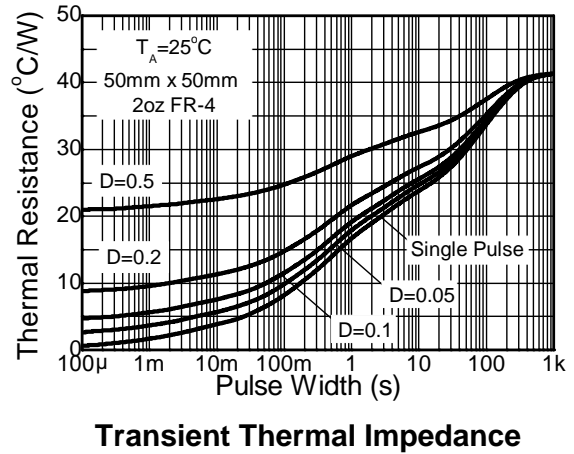
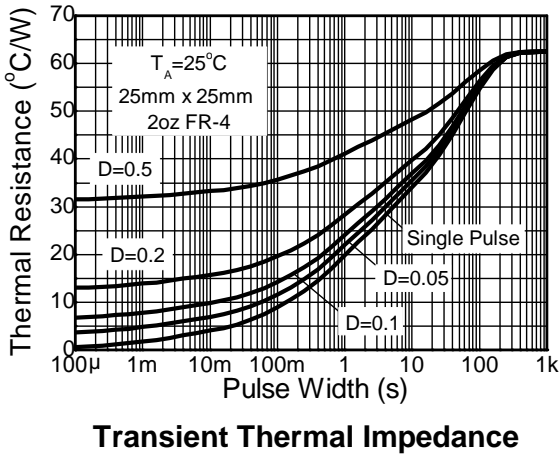
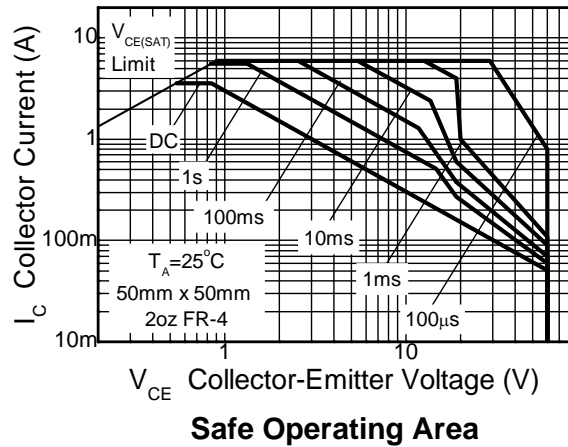
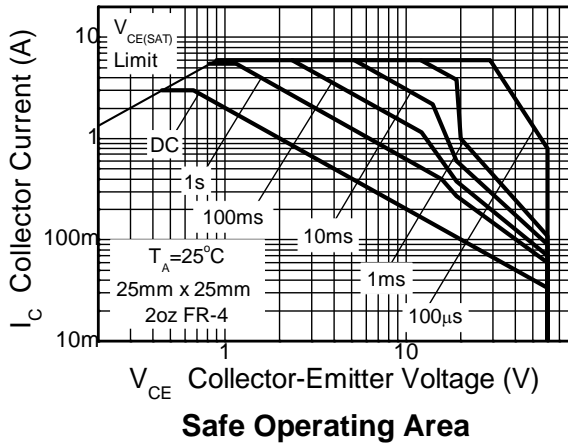
Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 6)	P _D	2	W
	(Note 7)		3	W
Thermal Resistance, Junction to Ambient	(Note 6)	R _{θJA}	62.5	°C/W
	(Note 7)		41.7	°C/W
Thermal Resistance, Junction to Leads	(Note 8)	R _{θJL}	12.9	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 9)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted with the collector lead on 25mm x 25mm 2oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in steady-state.
 7. Same as Note 6, except the device is mounted on 50mm x 50mm 2oz copper.
 8. Thermal resistance from junction to solder-point (at the end of the collector lead).
 9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

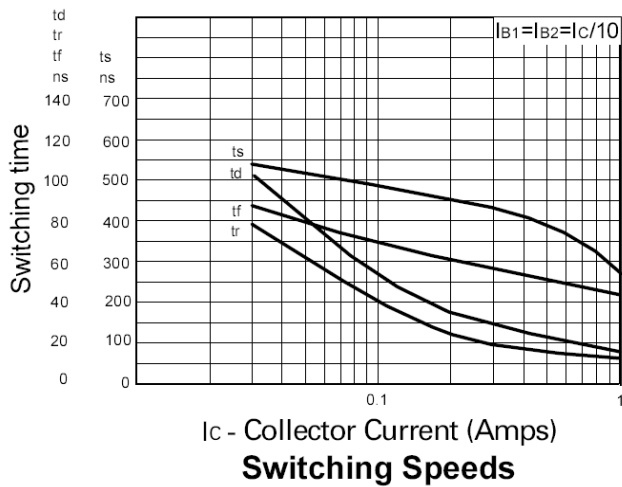
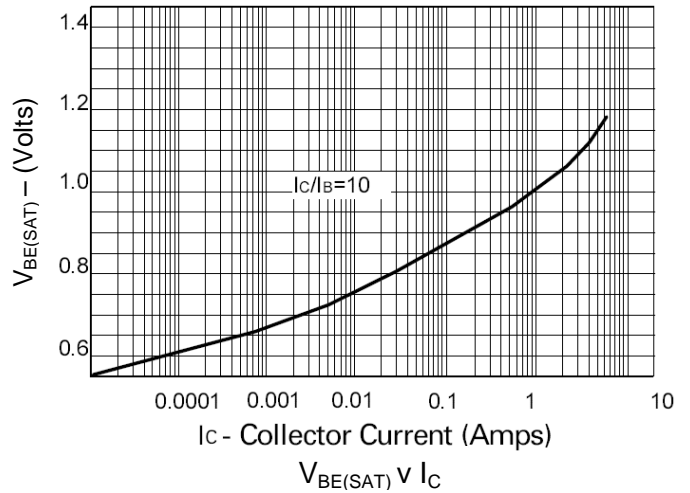
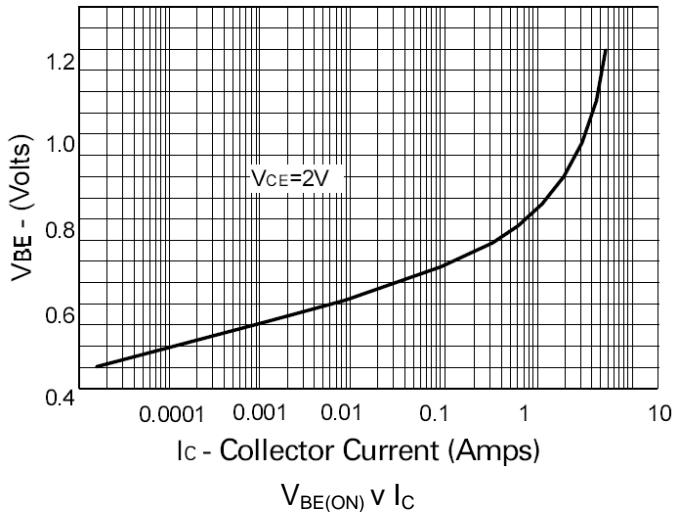
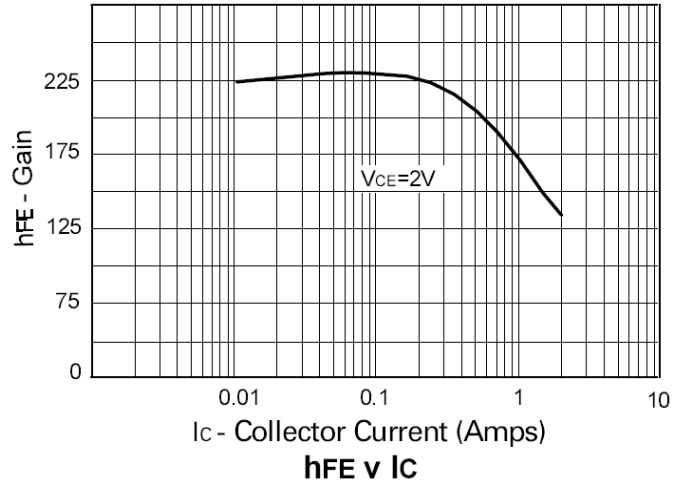
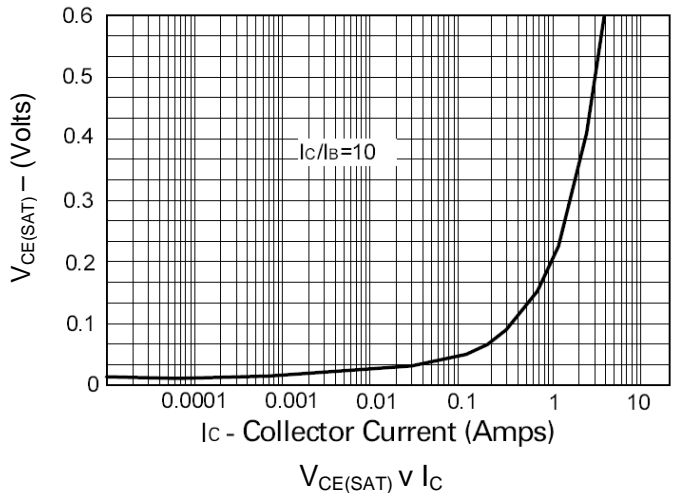


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	-80	—	—	V	$I_C = -100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 10)	BV_{CEO}	-60	—	—	V	$I_C = -10\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	-7	—	—	V	$I_E = -100\mu\text{A}$
Collector Cut-off Current	I_{CBO}	—	<-1	-100	nA	$V_{CB} = -60\text{V}$
		—	—	-10	μA	$V_{CB} = -60\text{V}, T_A = +100^\circ\text{C}$
Emitter Cut-off Current	I_{EBO}	—	<-1	-100	nA	$V_{EB} = -4\text{V}$
Collector-Emitter Saturation Voltage (Note 10)	$V_{CE(SAT)}$	—	-0.15	-0.3	V	$I_C = -1\text{A}, I_B = -100\text{mA}$
		—	-0.45	-0.6		$I_C = -3\text{A}, I_B = -300\text{mA}$
Base-Emitter Saturation Voltage (Note 10)	$V_{BE(SAT)}$	—	-0.9	-1.25	V	$I_C = -1\text{A}, I_B = -100\text{mA}$
Base-Emitter Turn-On Voltage (Note 10)	$V_{BE(ON)}$	—	-0.8	-1.0	V	$I_C = -1\text{A}, V_{CE} = -2\text{V}$
DC Current Gain (Note 10)	h_{FE}	70	200	—	—	$I_C = -50\text{mA}, V_{CE} = -2\text{V}$
		100	200	300		$I_C = -500\text{mA}, V_{CE} = -2\text{V}$
		80	170	—		$I_C = -1\text{A}, V_{CE} = -2\text{V}$
		40	150	—		$I_C = -2\text{A}, V_{CE} = -2\text{V}$
Current Gain-Bandwidth Product	f_T	100	140	—	MHz	$V_{CE} = -5\text{V}, I_C = -100\text{mA}$ $f = 100\text{MHz}$
Turn-On Time	t_{ON}	—	40	—	ns	$V_{CC} = -10\text{V}, I_C = -500\text{mA}$
Turn-Off Time	t_{OFF}	—	450	—	ns	$I_{B1} = I_{B2} = -50\text{mA}$
Output Capacitance	C_{OBO}	—	—	30	pF	$V_{CB} = -10\text{V}, f = 1\text{MHz}$

Note: 10. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

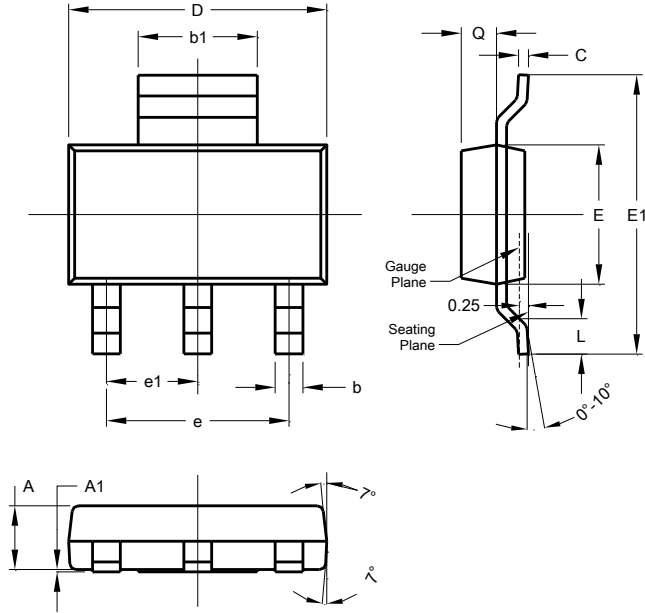
Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT223



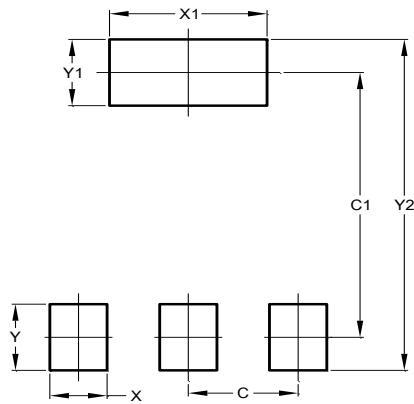
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Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT223



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

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